

PHYSICAL VERIFICATION AND DFM CLOSURE OF COMPLEX MOBILE CORES

The Customer:

A world leader of wireless and CDMA technologies

The Application:

Targeting the true 64 bit architecture for advanced cell phone chips with different processors for different market segments

Design specifics:

Two stages of tape-out process - Base Layer (BTO) & Metal Layer (MTO)

Mirafra's responsibility:

- Complete ownership of blocks for the following closure at MTO stage
- Physical verification / DFM (Static and Dynamic IR, Signal/Power EM) signoff
- ECOs for setup/hold/DRV issues

Tools used:

Synopsys IC-compiler, Synopsys PTSI, Cadence LEC, Cadence CLP and Redhawk

Engagement Model:

TNM, one block per person for a week time for each closure.